



## Material Declaration Certificate for Semiconductor Products

Winbond Electronics Corp. certifies that semiconductor products designated by Winbond as "Pb-Free" are compliant with the requirements of the European Union's Restriction on Use of Hazardous Substances ("RoHS") Directive, 2002/95/EC.

RoHS Restricted Substances	Threshold, Homogeneous Level
Cadmium	< 100 ppm
Hexavalent Chromium	<1000 ppm
Lead	< 1000 ppm
Mercury	< 1000 ppm
Polybrominated Biphenyls (PBBs)	<1000 ppm
Polybrominated Diphenyl Ethers (PBDEs)	< 1000 ppm

For Winbond semiconductor products NOT designated as "Pb-Free", these products are RoHS compliant with the exception of Lead (Pb) which may be found in the leadframe plating or solder balls.

Winbond's packing materials (boxes, trays, etc.) comply with the requirements of EU Directive 2004/12/EC concerning Packaging and Packaging Waste. The total concentration of Cadmium, Hexavalent Chromium, Lead and Mercury are less than 100 ppm.

Signature:

A handwritten signature in black ink, appearing to read "Rueyway Lin".

Name/Title: Dr. Rueyway Lin, Vice-President, QRA and ESH

Date: June 21, 2006